Our Innovations are Your Solutions™

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For Immediate Release

Global Circuit Innovations, Inc. Attains ISO 9001:2008 Registration

Semiconductor Solutions Provider Strengthens Their Commitment to Quality Management

Colorado Springs, CO — March 12, 2014 —Global Circuit Innovations™ (GCI), a market leader in offering cost effective semiconductor solutions for extreme environment applications and obsolescence, today announced it has become ISO 9001:2008 certified.

ISO 9001:2008 is recognized by organizations worldwide as ***the*** quality management standard. GCI's certification covers the processes used in the assembly and sale of their proprietary semiconductor die extraction and re-assembly in addition to conductive diamond plating.

"ISO 9001:2008 certification was an important milestone that demonstrated not only our dedication to provide quality products and services to our customers, but truly reflects on GCI's talented staff that worked tirelessly to develop, document and implement quality processes," said Jeff Murphy, GCI's Vice President of Operations. "As our products and services gain wider market acceptance, it will remain GCI's top priority to maintain and continuously improve our processes."

"Our markets and existing customers have come to expect GCI to not only supply quality services, but to also continue to develop cost effective technology solutions that allow semiconductors to perform in harsh environments or replace semiconductor devices that have become obsolete avoiding major redesign efforts," said Erick Spory, GCI's Founder and CTO. "Having ISO 9001:2008 certification in place will help us ensure that GCI will continue to demonstrate our levels of excellence while continuing to improve processes over the long term."

About Global Circuit Innovations™

Global Circuit Innovations™ (GCI) uses advanced technologies to provide cost effective Integrated Circuit (IC) products and services for defense, industrial and commercial electronic applications with the highest possible levels of reliability and survivability.

GCI's current products and services include: die harvesting from plastic or hermetic package without damaging the die and reassembly into the desired package, environmentally hardened Integrated Circuit (IC) products with increased survivability above 200C, die thinning services, Integrated Circuit (IC) assembly, IC and electronic system failure analysis, IC and PC board reverse engineering, and Conductive Diamond Plating (CDP).

Founded in 2006, Global Circuit Innovations is privately held and based in Colorado Springs, CO.

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For more information, visit: http://www.GCI-Global.com

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